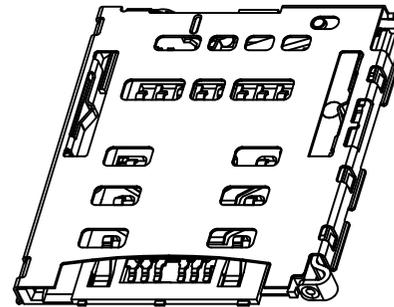
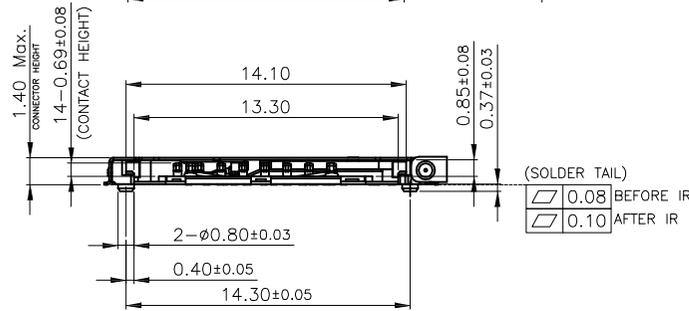
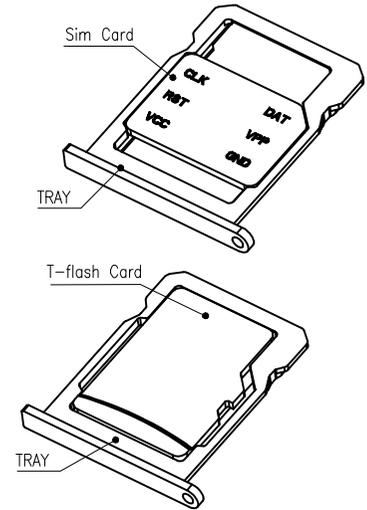
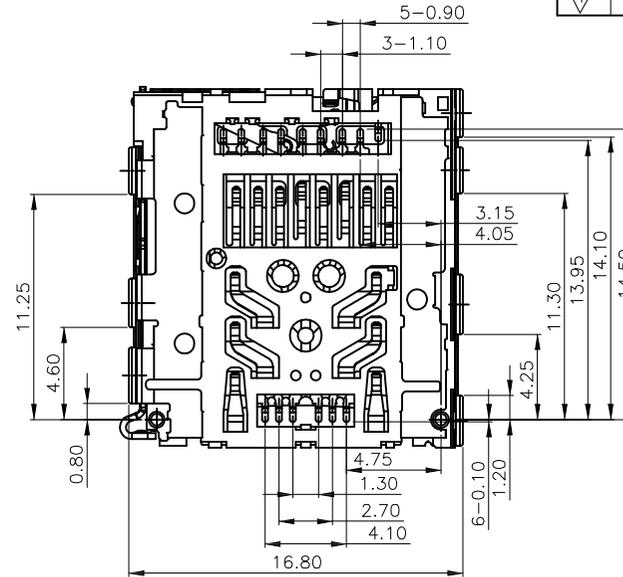
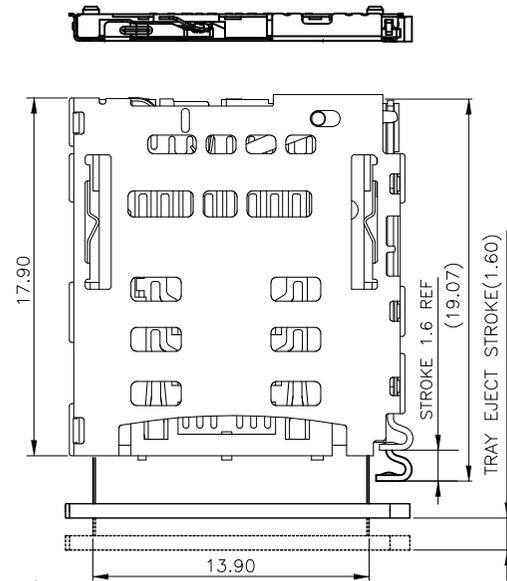


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
▽	PROPOSE ONLY	ALLEN	2013.08.04



- NOTES:
- FINISH
 - CONTACT: CONTACT AREA: Au 10u' Min.; SW AREA: Au 5u' Min.; GOLD PLATING ON SOLDER AREA, 3u' Min.
 - SHELL: SW AREA: 3u' Min.; SOLDER AREA: Au 3u' Min.
 - ELECTRICAL REQUIREMENTS:
 - CURRENT RATING: 0.3A PER PIN.
 - CONTACT RESISTANCE: 60 mOhm MAX. AFTER TEST:100 mOhm MAX SWITCH RESISTANCE : 100 mOhm MAX. AFTER TEST:150 mOhm MAX
 - INSULATION RESISTANCE: 1000 MOhm MIN.200 VDC FOR 1 MINUTE.
 - WITHSTANDING STRENGTH: 500V AC FOR 1 MINUTE.
 - MECHANICAL REQUIREMENTS:
 - TRAY MATING FORCE: 0.2~ 1.0kgf .; TRAY UNMATING FORCE: 0.4~1.0kgf OPERATING FORCE: 0.4~1.0 kgf . THE RESORPTION DISTANCE OF THE TRAY : 0.4mm MIN
 - DURABILITY: 3,000 CYCLES MIN.
 - ENVIRONMENT REQUIREMENTS:
 - OPERATING TEMP.: -30°C TO +85°C
 - STORAGE TEMPERATURE: -40°C TO +85°C
 - UNLESS OTHERWISE SPECIFIED, ALL DIMENSIONS ARE IN mm.
 - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

5	CAM	1	SUS304-H	NO PLATING
4	LEVER	1	SUS301-H	NO PLATING
3	SHELL	1	SUS301-H	SWITCH AREA: Au 3u' min. SOLDER AREA: Au 3u' min.
2	I/M HOUSING	1	LCP	BLACK COLOR, UL94 V-0
1	CONTACT	1	NKT322-EH	CONTACT AREA: Au 10u' min. SWITCH AREA: Au 5u' min. SOLDER AREA: Au 3u' min.
ITEM	PART NAME	Q'TY	MATERIAL	FINISH

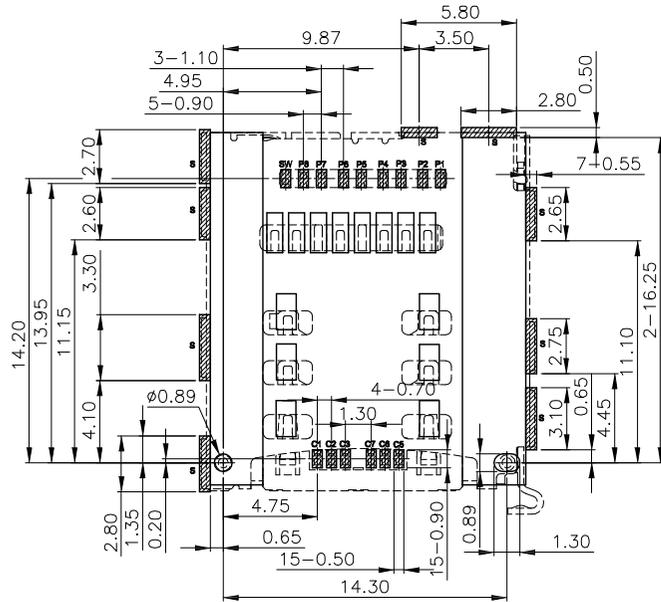
UNLESS OTHERWISE SPECIFIED TOLERANCES

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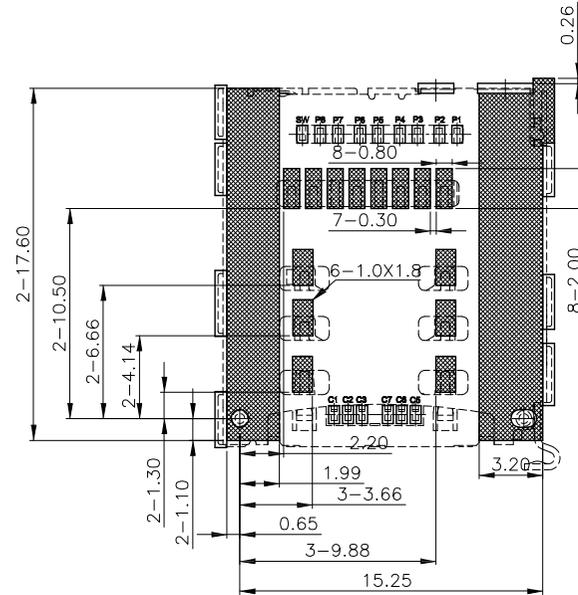
DECIMALS:	ANGLES:	TITLE	T-Flash 1.4H(Push Lever) Card CONN.		
X :±0.5	X :±2'	DWN	ALLEN	PART NO. CS-203-T	
X.X :±0.20	X.X :±1'	CHKD	KEVIN	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	ERIC.W	SIZE: A3	SHEET: 1 OF 3
					REV: A1

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REV.	ECN NO OR DESCRIPTION	REVISED	DATE
1	PROPOSE ONLY	ALLEN	2013.08.04



RECOMMENDED PCB LAYOUT(SOLDER AREA)
(TOLERANCE: ±0.05)
PASTE BOARD THICKNESS 0.10mm.
 SOLDER AREA



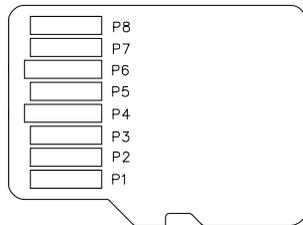
RECOMMENDED PCB LAYOUT(NO PATTERNS)
(TOLERANCE: ±0.05)
 NO PATTERNS

CONNECTOR PIN ASSIGNMENT:

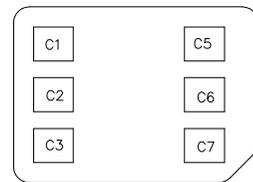
ITEM	FUNCTION
MSD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
SW	TRAY DETECTION SW
S	SHELL GND
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM

CARD PIN ASSIGNMENT:

ITEM	FUNCTION
MSD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM

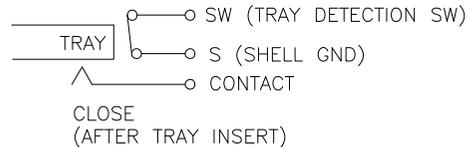
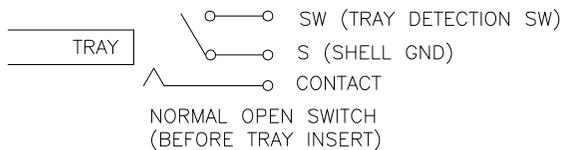


MSD CARD ELECTRICAL



NANO SIM CARD ELECTRICAL

CIRCUIT DIAGRAM FOR DETECT SWITCHES



UNLESS OTHERWISE SPECIFIED TOLERANCES

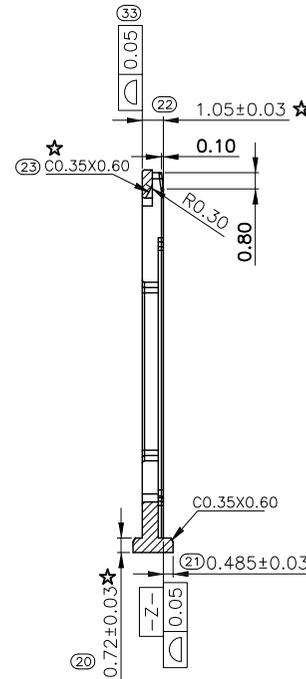
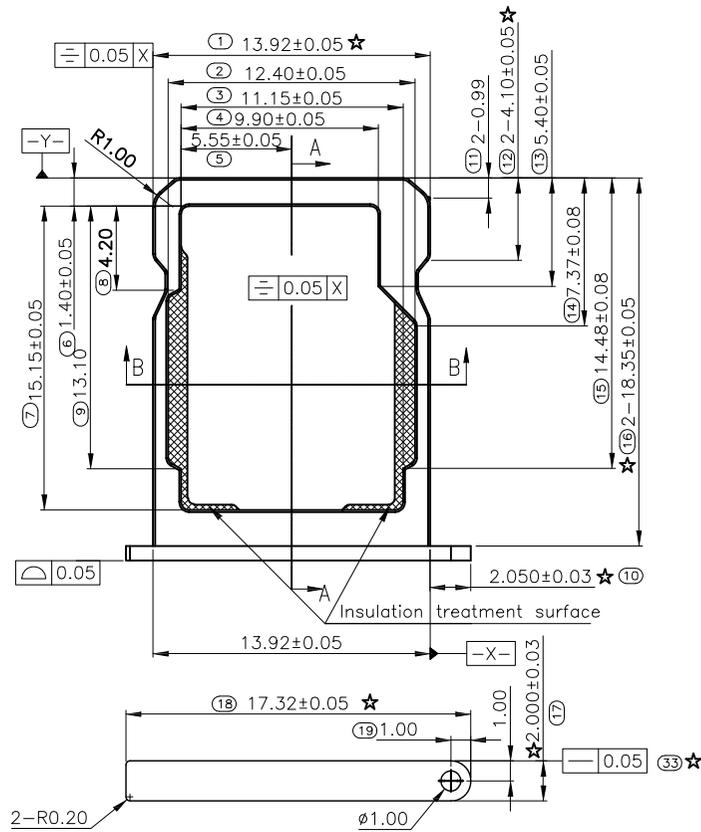
DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.10	

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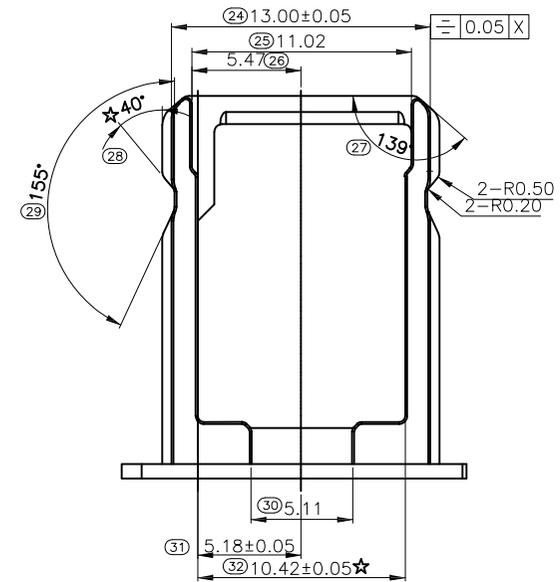
TITLE	T-Flash 1.4H(Push Lever) Card CONN.			
DWN	ALLEN	PART NO. CS-203-T		
CHKD	KEVIN	SCALE:1:1	UNIT: mm	
APVD	ERIC.W	SIZE: A3	SHEET: 2 OF 3	REV: A1

CUSTOMER COPY

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
▽	PROPOSE ONLY	ALLEN	2013.08.04

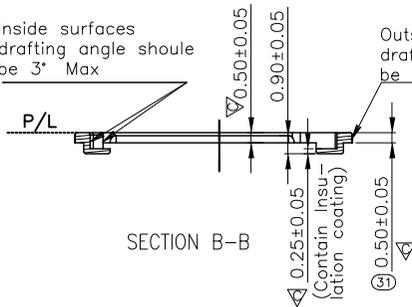


SECTION A-A



- NOTES: 1.Material: SUS17-4PH
 2.Finish: Referce to customer request;
 The roughness ∇ of all surfaces should meet $Ra < 0.5\mu m$; $Rz < 4.0\mu m$
 3.Harmful material control please follow "SS-00259-1"
 4.The dimension marked \star should be checked by QC and process engineer,and should also check the CPK data.

Inside surfaces drafting angle shoule be 3° Max
 Outside surfaces drafting angle shoule be 2° Max



SECTION B-B



3	REEL	PLOYSTYRENE
2	COVER TAPE	PLOYSTYRENE
1	CARRIER TAPE	THERMOPLASTIC
ITEM	P/N	MATFRIAL

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.10	

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TITLE	T-Flash 1.4H(Push Lever) Card CONN.			
DWN	ALLEN	PART NO.	CS-203-T	
CHKD	KEVIN	SCALE:1:1	UNIT: mm	
APVD	ERIC.W	SIZE: A3	SHEET: 3 OF 3	REV: A1

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